

MAY 28 2002

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of  
PATENTS & TRADEMARKS

Eiji HAYASHI

Serial No.: 09/810,454

Group Art Unit: 1725

Filed: March 19, 2001

Examiner: Jonathan J. Johnson

For: FLIP CHIP BONDING METHOD

THE COMMISSIONER FOR PATENTS AND TRADEMARKS  
Washington, DC 20231

RECEIVED

MAY 29 2002

TC 1700

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

No additional fee is required.  
 Applicant is entitled to small entity status under 37 CFR 1.27  
 Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	2	20	0	\$18.00 =	\$0.00
Independent Claims	1	3	0	\$84.00 =	\$0.00
Multiple claims newly presented					\$0.00
Fee for extension of time					\$0.00
					\$0.00
Total of Above Calculations					\$0.00

Please charge my Deposit Account No. 500417 in the amount of \$0.00. An additional copy of this transmittal sheet is submitted herewith.

The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

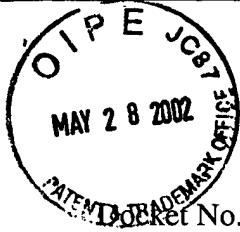
MCDERMOTT, WILL &amp; EMERY

*Bernard P. Codd*

Bernard P. Codd

Registration No. 46,429

600 13<sup>th</sup> Street, N.W.  
 Washington, DC 20005-3096  
 (202)756-8000 BPC:rrh  
 Facsimile: (202)756-8087  
 Date: May 28, 2002



4/1 5/30/02  
11

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :  
Eiji HAYASHI :  
Serial No.: 09/810,454 : Group Art Unit: 1725  
Filed: March 19, 2001 : Examiner: Jonathan J. Johnson  
For: FLIP CHIP BONDING METHOD

AMENDMENT

Commissioner for Patents  
Washington, DC 20231

Sir:

The following Amendments and Remarks are filed in response to the Office  
Action dated February 26, 2002.

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 1, line 17, with the following  
rewritten paragraph:

--However, the conventional flip chip bonding method uses flux. Flux removes  
oxide films on surfaces of solder bumps and to facilitate connections by solder. However, if  
the quantity of the flux is not optimized or a step of cleaning is not controlled, there are  
problems that the flux is left as propellant fouling after the step of cleaning, and the  
propellant fouling prevents a sealing resin from being injected in a later step, whereby voids  
are induced, yield is dropped, and reliability is spoiled.--

**RECEIVED**

MAY 29 2002

TC 1700